## **Amplifier Transistors**

## **NPN Silicon**

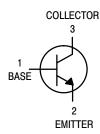
#### **Features**

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



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# 1 2

SOT-23 (TO-236) CASE 318 STYLE 6

## **MAXIMUM RATINGS**

Rating	Symbol	6428LT1	6429LT1	Unit
Collector – Emitter Voltage	$V_{CEO}$	50 45		Vdc
Collector - Base Voltage	$V_{CBO}$	60 55		Vdc
Emitter – Base Voltage	$V_{EBO}$	6.0		Vdc
Collector Current – Continuous	I <sub>C</sub>	200		mAdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Total Device Dissipation FR-5 Board (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Derate above 25 C		1.0	IIIVV/ C
Thermal Resistance, Junction–to–Ambient	$R_{ heta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T <sub>A</sub> = 25°C	P <sub>D</sub>	300	mW
Derate above 25°C		2.4	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

- 1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina = 0.4  $\times$  0.3  $\times$  0.024 in. 99.5% alumina.

## **MARKING DIAGRAM**



XXX = Specific Device Code MMBT6428LT1 - 1KM NSV/MMBT6429LT1 - M1L

M = Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

#### **ORDERING INFORMATION**

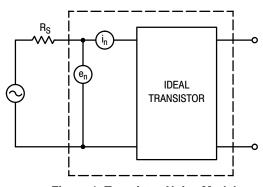
Device	Package	Shipping <sup>†</sup>
MMBT6428LT1G	SOT-23 (Pb-Free)	3000 Tape & Reel
MMBT6429LT1G	SOT-23 (Pb-Free)	3000 Tape & Reel
NSVMMBT6429LT1G	SOT-23 (Pb-Free)	3000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS				•	•
Collector – Emitter Breakdown Voltage $(I_C = 1.0 \text{ mAdc}, I_B = 0)$ $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	MMBT6428 MMBT6429 / NSVMMBT6429	V <sub>(BR)CEO</sub>	50 45	- -	Vdc
Collector – Base Breakdown Voltage ( $I_C = 0.1 \text{ mAdc}, I_E = 0$ ) ( $I_C = 0.1 \text{ mAdc}, I_E = 0$ )	MMBT6428 MMBT6429 / NSVMMBT6429	V <sub>(BR)CBO</sub>	60 55	- -	Vdc
Collector Cutoff Current (V <sub>CE</sub> = 30 Vdc)		I <sub>CES</sub>	_	0.1	μAdc
Collector Cutoff Current (V <sub>CB</sub> = 30 Vdc, I <sub>E</sub> = 0)		I <sub>CBO</sub>	_	0.01	μAdc
Emitter Cutoff Current (V <sub>EB</sub> = 5.0 Vdc, I <sub>C</sub> = 0)		I <sub>EBO</sub>	-	0.01	μAdc
ON CHARACTERISTICS					
DC Current Gain ( $I_C = 0.01 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc}$ )	MMBT6428 MMBT6429 / NSVMMBT6429	h <sub>FE</sub>	250 500	- -	_
$(I_C = 0.1 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc})$	MMBT6428 MMBT6429 / NSVMMBT6429		250 500	650 1250	
$(I_C = 1.0 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc})$	MMBT6428 MMBT6429 / NSVMMBT6429		250 500	_ _	
$(I_C = 10 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc})$	MMBT6428 MMBT6429 / NSVMMBT6429		250 500	- -	
Collector – Emitter Saturation Voltage ( $I_C = 10 \text{ mAdc}$ , $I_B = 0.5 \text{ mAdc}$ ) ( $I_C = 100 \text{ mAdc}$ , $I_B = 5.0 \text{ mAdc}$ )		V <sub>CE(sat)</sub>	- -	0.2 0.6	Vdc
Base – Emitter On Voltage (I <sub>C</sub> = 1.0 mAdc, V <sub>CE</sub> = 5.0 Vdc)		V <sub>BE(on)</sub>	0.56	0.66	Vdc
SMALL-SIGNAL CHARACTERISTICS					
Current – Gain – Bandwidth Product (I <sub>C</sub> = 1.0 mAdc, V <sub>CE</sub> = 5.0 Vdc, f = 100 MHz)		f <sub>T</sub>	100	700	MHz
Output Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)		$C_{obo}$	_	3.0	pF
Input Capacitance (V <sub>EB</sub> = 0.5 Vdc, I <sub>C</sub> = 0, f = 1.0 MHz)		C <sub>ibo</sub>	_	8.0	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

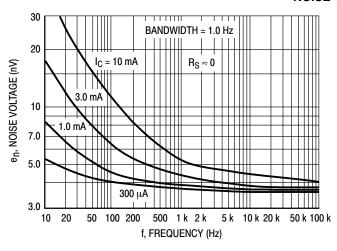


**Figure 1. Transistor Noise Model** 

## **NOISE CHARACTERISTICS**

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}C)$ 

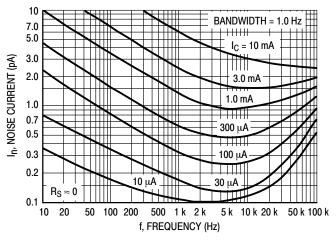
#### **NOISE VOLTAGE**



BANDWIDTH = 1.0 Hz 20 en, NOISE VOLTAGE (nV)  $R_S \approx 0\,$ f = 10 Hz 10 100 Hz 7.0 1.0 kHz 5.0 3.0 0.01 0.02 0.05 0.1 0.2 0.5 1.0 5.0 10 IC, COLLECTOR CURRENT (mA)

Figure 2. Effects of Frequency

**Figure 3. Effects of Collector Current** 



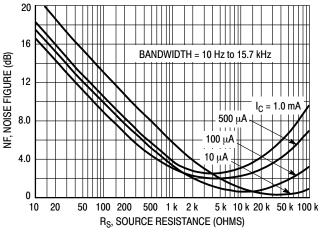
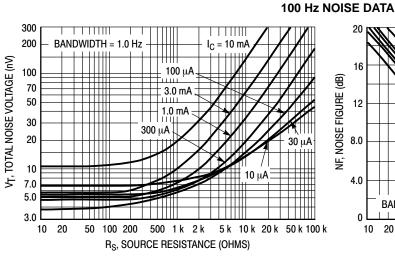


Figure 4. Noise Current

Figure 5. Wideband Noise Figure



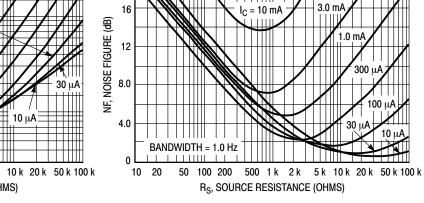


Figure 6. Total Noise Voltage

Figure 7. Noise Figure

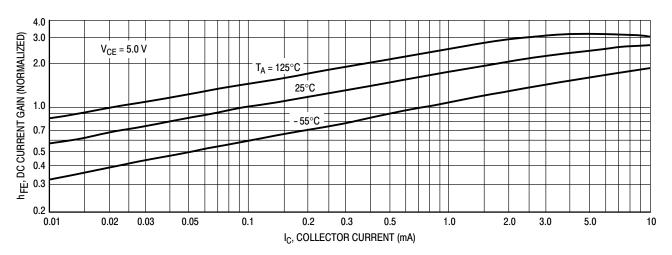


Figure 8. DC Current Gain

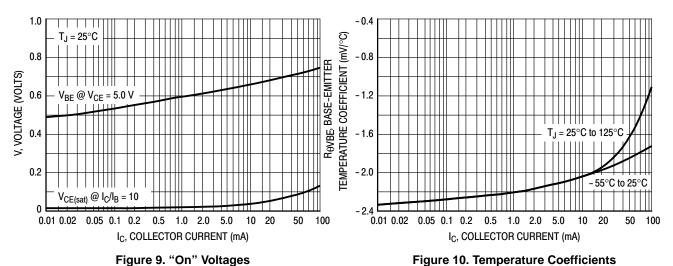


Figure 9. "On" Voltages

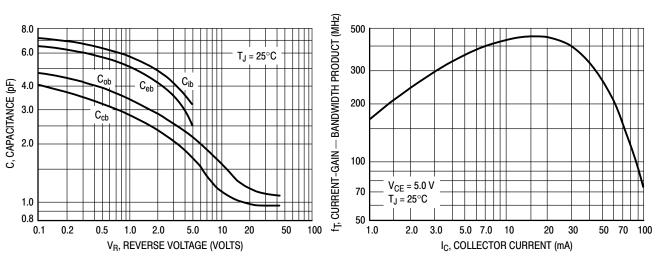
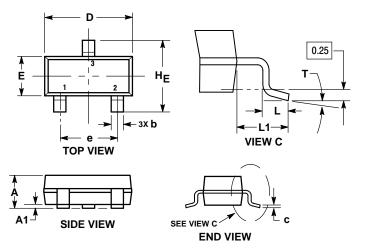


Figure 11. Capacitance

Figure 12. Current-Gain — Bandwidth Product

## PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AR** 



- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
- PROTRUSIONS, OR GATE BURRS

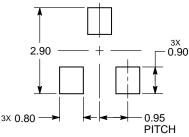
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0°	-	10°	0°	-	10°

STYLE 6:

PIN 1. BASE

**EMITTER** COLLECTOR

### **RECOMMENDED** SOLDERING FOOTPRINT\*



**DIMENSIONS: MILLIMETERS** 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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